



Agency Approvals

Agency	Agency File Number
71	E128662

Maximum Ratings and Thermal Characteristics

(T_△=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Operating Junction	T_{J}	-55 to 125	°C
Storage Temperature Range	T _{STG}	-55 to 150	C
Current Rating ¹	I _{PP}	6	kA
Typical Thermal Resistance Junction to Lead	R _{eJL}	10	°C/W
Typical Thermal Resistance Junction to Ambient	R _{eJA}	50	°C/W

Description

The LTKAK6 series offers superior clamping characteristics over standard S.A.D. technologies by virtue of the Littelfuse FoldbakTM technology, which provides a clamping voltage lower than the avalanche voltage (but above the rated working voltage). Therefore, any voltage rise due to increased current conduction is contained to a minimum, providing the best possible protection level.This LTKAK6 series can be combined in series or parallel solutions to offer various clamping levels and surge withstand options.

The LTKAK6 SMT package provides a more compact PCB layout than typical through-hole AK TVS components.

Features

- High Power TVS designed in a surface mount and compact SMTO-218 package
- Patent pending package design
- FoldbakTM Technology for superior clamping characteristics
- Tube or tape and reel pack options available
- Ideal for automatic pick and place assembly and reflow process to reduce the manufacturing cost and increase the soldering quality as compared to axial leaded packages

- Low clamping and slope resistance.
- Sharp breakdown voltage.
- Meet MSL level1, per J-STD-020, LF maximum peak of 245°C
- Pb-free E3 means 2nd level interconnect is Pb-free and the terminal finish material is tin(Sn) (IPC/JEDEC J-STD-609A.01)
- UL Recognized compound meeting flammability rating

Note:

1. Rated min $\rm I_{\rm pp}$ measured with 8/20µs pulse.

Electrical Characteristics (T_A=25°C unless otherwise noted)

Part Numbers	Standoff Voltage (V _{so})	Max. Reverse Leakage (I _R) @V _{SO}		kdown Voltage @ I _T	Test Current I _T	Max. Clamping Voltage V _C @ (I _{PP})	Max. Temp Coefficient of V _{BR}	Max. Capacitance 0V Bias 10kHz
	(V)	¨(μ A) ຶ	Min Volts	Max Volts	(mA)	Volts	(%/°C)	(nF)
LTKAK6-058C	58	10	64	70	10	110	0.1	6.5
LTKAK6-066C	66	10	72	80	10	120	0.1	5.5
LTKAK6-076C	76	10	85	95	10	140	0.1	4.5

Note: Using 8/20 waveshape as defined in IEC 61000-4-5 2nd edition.

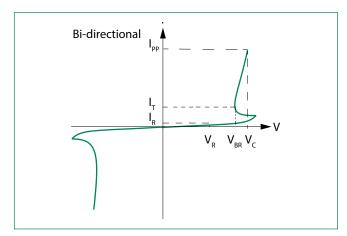
Surge Ratings

	Max Peak Pulse Current (I _{PP})			
Part Numbers	(80/20μS) (A)	(10/350µS) (A)		(10/1000µS) (A)
	Min	Min	Тур	Min
LTKAK6-058C	6,000	900	1,100	430
LTKAK6-066C	6,000	900	1,100	430
LTKAK6-076C	6,000	900	1,100	430



LTKAK6 Series SMT0-218 - 6KA

I-V Curve Characteristics



P_{PPM} Peak Pulse Power Dissipation --

Max power dissipation

V_R Stand-off Voltage --

Maximum voltage that can be applied to the TVS without operation

V_{BR} Breakdown Voltage -- Maximum voltage that flows though the TVS at a specified test current (I₇)

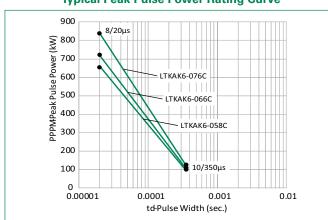
V_c Clamping Voltage --Peak voltage measured across the TVS at a specified lppm (peak impulse current)

Reverse Leakage Current --

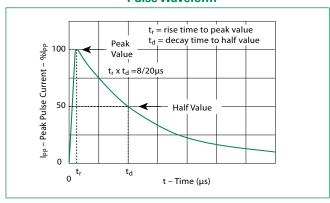
Current measured at V.

Ratings and Characteristic Curves (T_A=25°C unless otherwise noted)

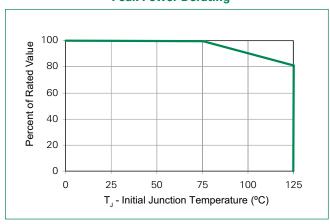
Typical Peak Pulse Power Rating Curve



Pulse Waveform



Peak Power Derating

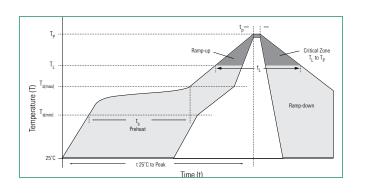


Please contact Littelfuse for reliability or FIT/MTBF data , the performance is subject to vary and depends on the end customers' application condition

LTKAK6 Series SMT0-218 - 6KA

Soldering Parameters

Reflow Condition		Lead-free assembly
	-Temperature Min (T _{s(min)})	150°C
Pre Heat	-Temperature Max (T _{s(max)})	200°C
	-Time (min to max) (t _s)	60 – 180 secs
Average ram	3°C/second max	
T _{S(max)} to T _A -	3°C/second max	
Reflow	- Temperature (T _A) (Liquidus)	217°C
nellow	-Time (min to max) (t _s)	60 – 150 seconds
Peak Tempera	ature (T _P)	245 ^{+0/-5} °C
Time within	30 seconds Max	
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T _P)		8 minutes Max.
Do not excee	ed	245°C



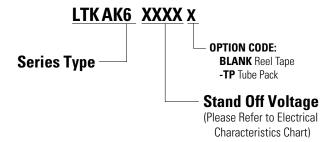
Flow/Wave Soldering (Solder Dipping)

Peak Temperature :	260°C
Dipping Time :	10 seconds
Soldering :	1 time

Physical Specifications

Weight	Contact manufacturer
Case	Epoxy encapsulated
Terminal	Tin plated lead, solderable per
leriiiilai	MIL-STD-202 Method 208

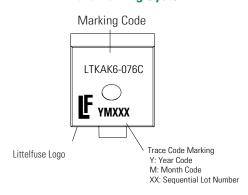
Part Numbering System



Physical Specifications

High Temp Storage	JESD22-A103
HTRB	JESD22-A108
MSL	JESDEC-J-STD020, Level 1
H3TRB	JESD22-A101
RSH	JESD22-B106

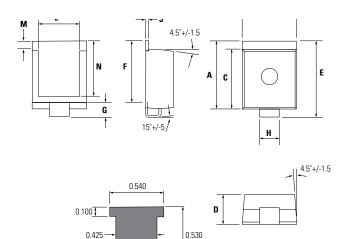
Part Marking System





LTKAK6 Series SMT0-218 - 6KA

Dimensions — SMTO-218



0.085

Dimension	Inches		Millimeters	
Dimension	Min	Max	Min	Max
Α	0.621	0.655	15.78	16.63
В	0.529	0.594	13.43	15.09
С	0.544	0.561	13.83	14.24
D	0.273	0.285	6.94	7.24
E	0.702	0.737	17.82	18.72
F	0.567	0.587	14.40	14.90
G	0.087	0.126	2.20	3.20
Н	0.193	0.222	4.89	5.65
J	0.028	0.033	0.72	0.85
L	0.400	0.440	10.17	11.17
M	0.073	0.112	1.85	2.85
N	0.510	0.533	12.95	13.55

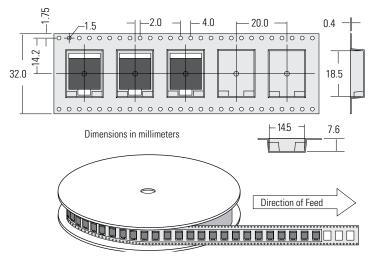
Note: Coplanarity of solder side is controlled within 0.08mm.

0.191

Packaging

Part Number	Weight	Packing Mode	Base Quantity
LTKAK6-xxxC	4.34g	Tape & Reel – 32mm/13" tape	400
LTKAK6-xxxC-TP	4.34g	Tube Pack	100(25/Tube)

Tape and Reel Specification



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>>Littelfuse(美国力特)